



# SOT1198-1

plastic thermal enhanced very thin quad flat package; no leads; 54 terminals; resin based

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN54R
<b>Package type industry code</b>	HVQFN54R
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	---
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	20-1-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.4	-	5.5	5.6	mm
E	package width	9.9	-	10	10.1	mm
A	seated height	0.75	-	0.8	0.9	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	54	-	

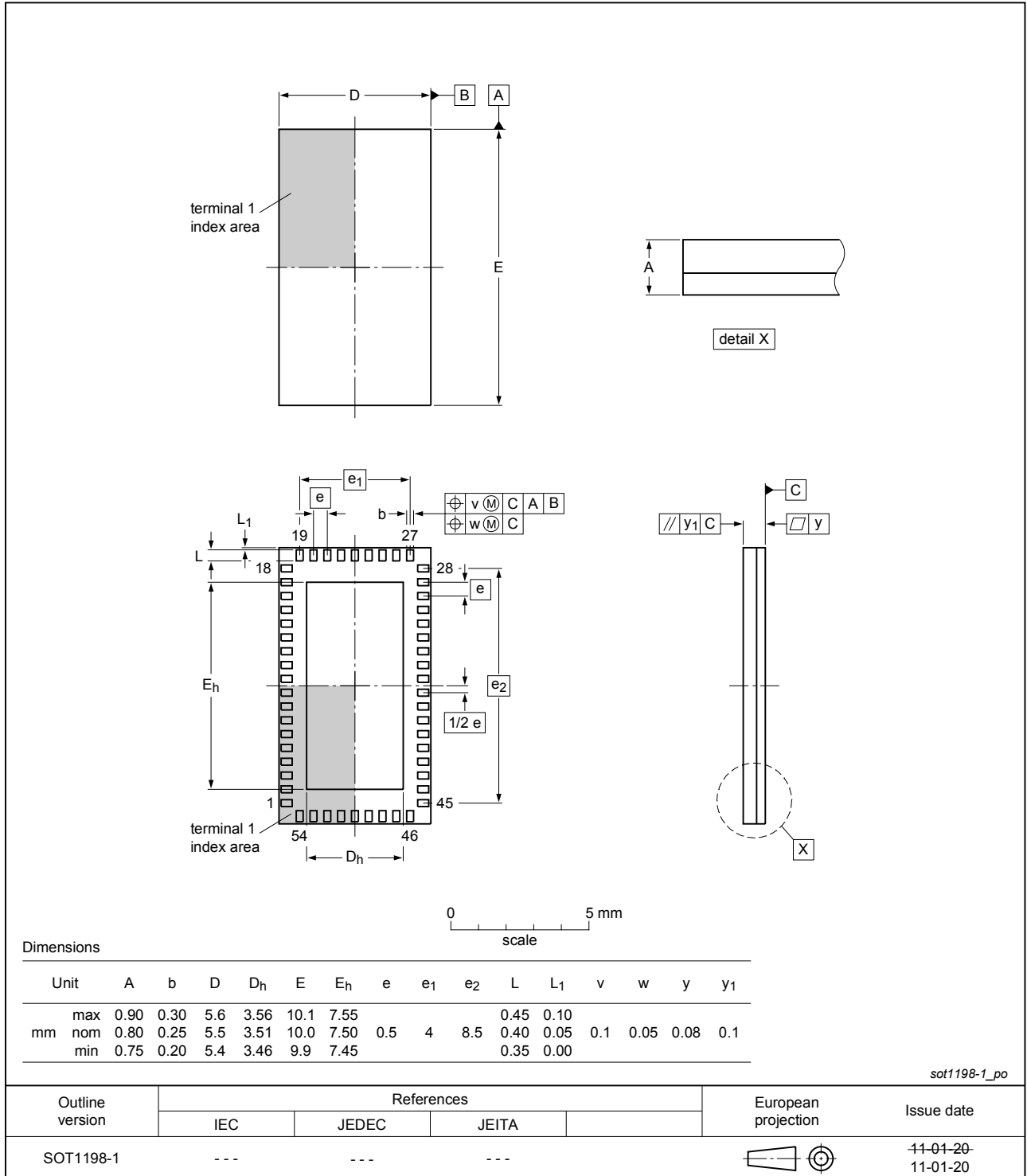


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## 2. Package outline

**HVQFN54R: plastic thermal enhanced very thin quad flat package; no leads; 54 terminals; resin based; body 5.5 x 10 x 0.8 mm**

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**Fig. 1. Package outline HVQFN54R (SOT1198-1)**

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### 3. Legal information

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